



Product presentation – ModCap HF

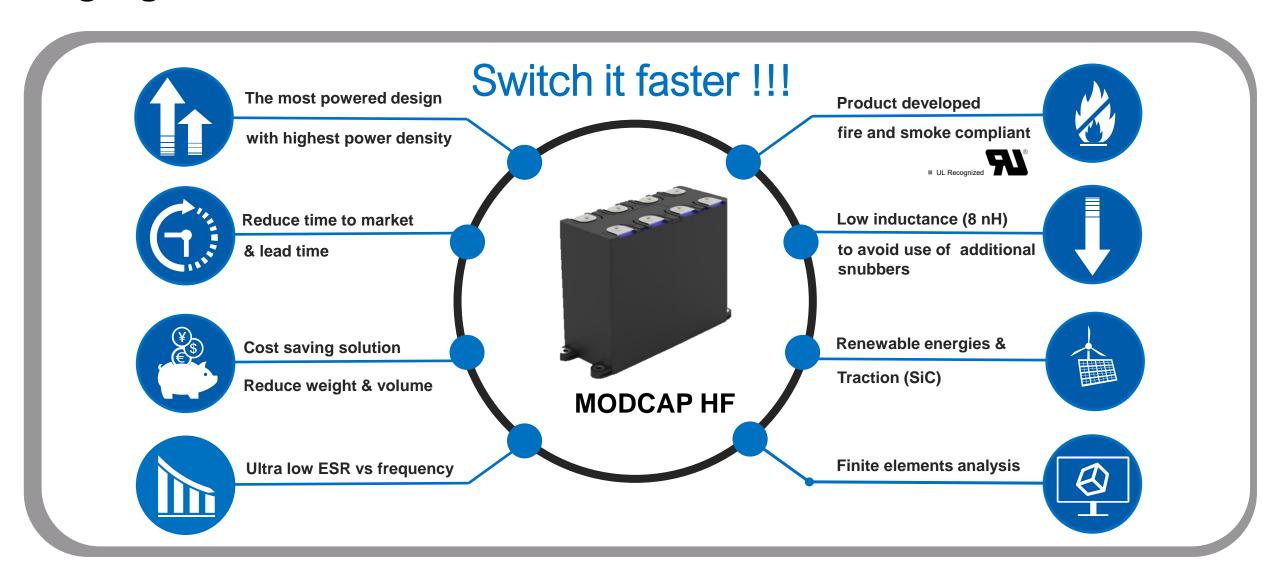
DCR Modular | New Modular High Frequency Series



Introducing the New Modular HF series Highligths

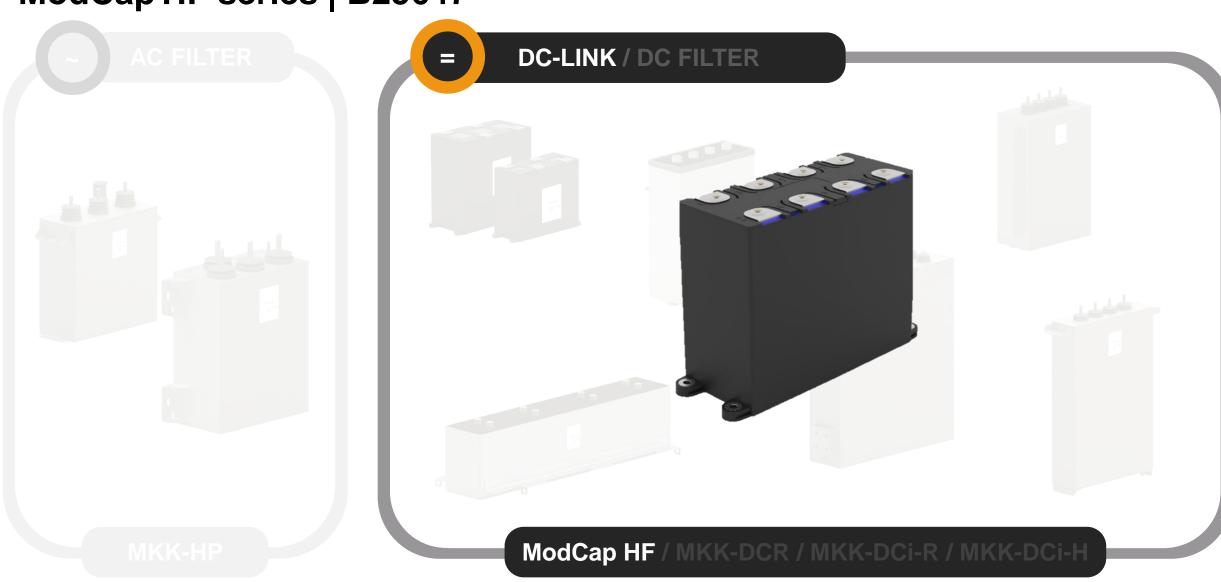








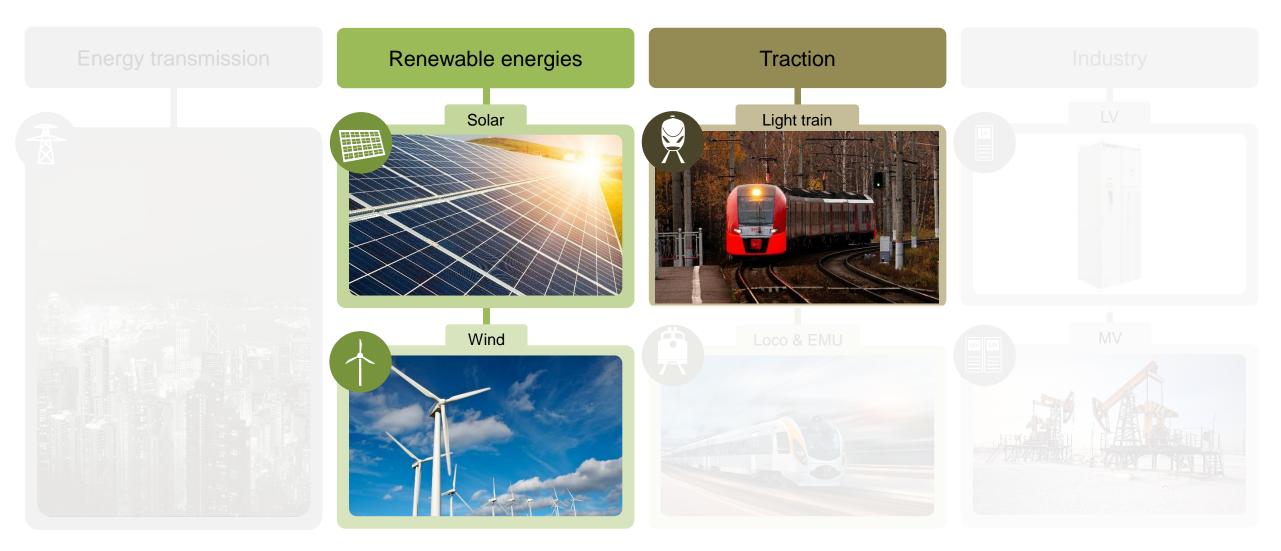
ModCap HF series | B25647



ModCa HF series | B25647 DC-Link applications













ModCap HF (dry-modular-high frequency)



Features

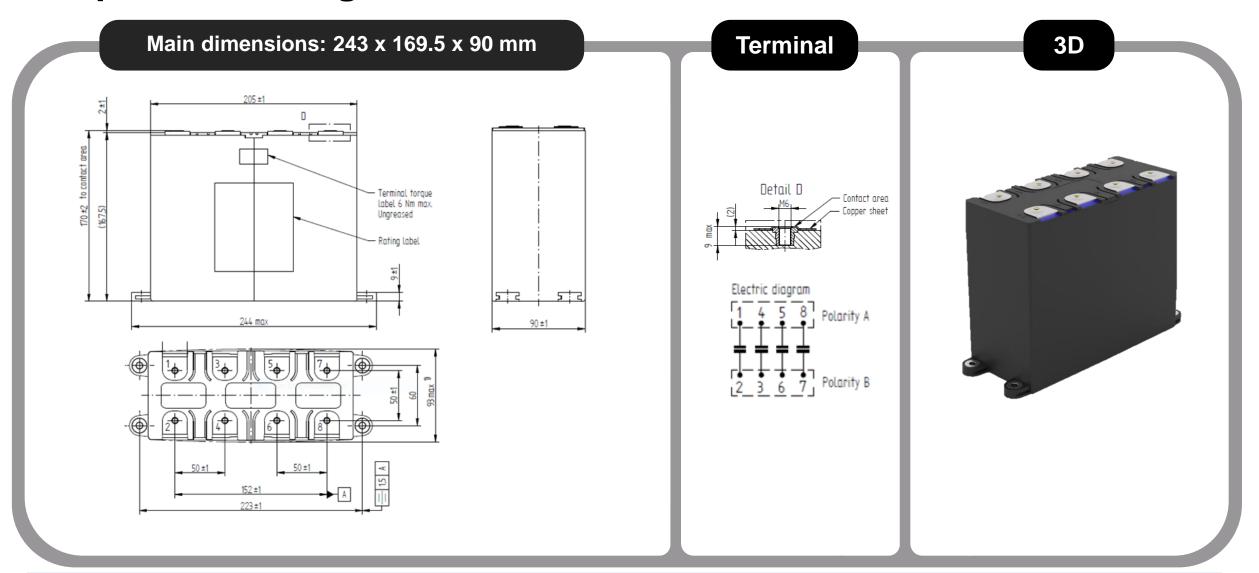
- Capacitance range from 640 μF up to 1850 μF and voltage from 900 V up to 1,600 V
- Low ESL (8 nH)
- Temperature range up to 90 °C hotspot
- IEC 61071, IEC 61881-1, EN 45545-2 HL3 R23 (fire and smoke), UL recognized
- Filled with polyurethane resin (dry technology)
- Plastic case (opened), 8 terminals construction
- Flat windings

Benefits

- High power density, high frequency performance
- Modular concept for parallelization
- Snubber avoidance / low voltage overshoot
- Lifetime up to 200,000 hours
- Finite elements analysis available for the whole series
- Specially recommended for SiC semiconductors
- Reduced time to market & lead time









Compact power unit



 Capacitors can be mounted very close to the power modules to reduce loop inductance.



→ Compact and scalable solution specially designed for SiC semiconductors



→ Less investment on cooling

Very short connection between capacitor and semi-conductor



→ Ultra Low inductance (8nH)

→ Snubber capacitors avoidance and suppression of HF resonance



Electromagnetic behavior of Modular HF Series

Electromagnetic: modelling



Customer benefits

Customer Input

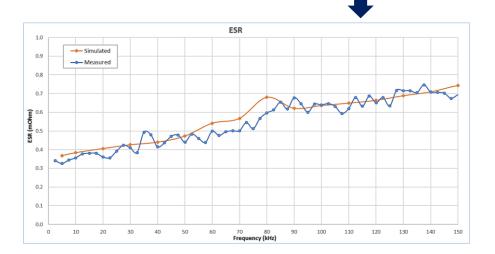
Current-frequency spectrum

TDK Input

Capacitor design

Simulation

Capacitor electrical model: including ESL and ESR Vs Freq Total losses and its internal distribution (must for accurate thermal simulation)

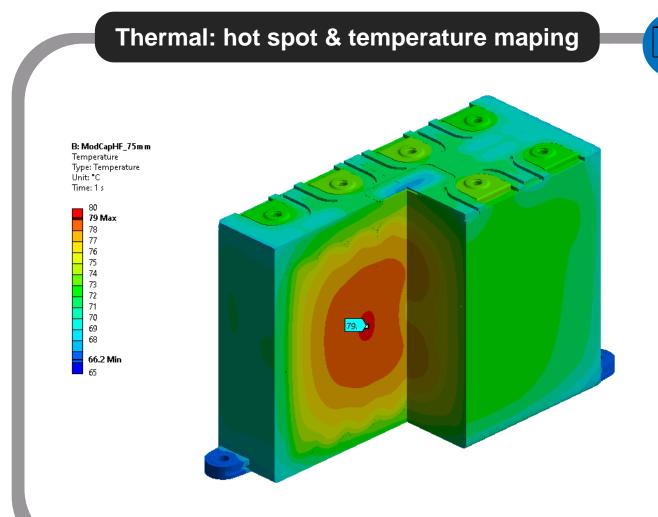


- Electromagnetic model available for specific simulation according to current-frequency spectrum defined by the customer.
- Capacitor electrical model available in time and frequency domain
- Losses at defined current-frequency spectrum and its internal distribution
- Graphs with simulated ESR fully available for further thermal calculations by calculating losses all along the complete range of frequency

Thermal behavior of Modular HF Series







Customer benefits

(3)

- Thermal model available for specific simulation according to spectrum and boundary conditions defined by the customer.
- Thermal simulations to be integrated as part of the type test report.
- Thermal Simulations may reduce the complexity and time of technical approvals, no further specific thermal stability test on lab.
- Detailed Temperature maping allows customer to estimate in advance hot spot areas
- Thermal Simulation to be done as per specific customer requirements (customized current spectrum and thermal boundary conditions)
- Heating Transference from bus bar may be analyzed in advance





ModCap HF: Construction C

Nominal voltage (V)	Capacitance ±10% (μF)	Nominal current (A)	Surge current (kA)	Repetitive peak current (kA)	Dimensions (LxWxH, mm)	Construction	Part Number
900	1850	210	225	5	205x90x170	С	B25647A9198K003
1000	1520	200	220	5	205x90x170	С	B25647A1158K003
1100	1200	190	215	5	205x90x170	С	B25647A1128K003
1250	940	180	210	5	205x90x170	С	B25647A1947K003
1350	880	170	205	5	205x90x170	С	B25647A1887K003
1600	640	160	200	5	205x90x170	С	B25647A1647K003



Get more info $\underline{\text{here}}$

